



Material Content Data Sheet



Sales Product Name	ESD3V3U1U-02LS E6327			Issued		29. August 2013		
MA#	MA000878272							
Package	PG-TSSLP-2-1			Weight*		0.15 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.57		5746	
	noble metal	gold	7440-57-5	0.003	2.23		22281	
	inorganic material	silicon	7440-21-3	0.010	6.60	9.40	66040	94066
leadframe	non noble metal	nickel	7440-02-0	0.036	23.97	23.97	239664	239664
wire	noble metal	gold	7440-57-5	0.003	1.90	1.90	18979	18979
encapsulation	organic material	carbon black	1333-86-4	0.001	0.57		5713	
	plastics	epoxy resin	-	0.012	7.71		77111	
	inorganic material	silicondioxide	60676-86-0	0.074	48.84	57.12	488351	571175
leadfinish	noble metal	gold	7440-57-5	0.004	2.71	2.71	27105	27105
plating	noble metal	silver	7440-22-4	0.007	4.90	4.90	49010	49010
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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